

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### **Listing of Claims:**

1. (currently amended) A packaged semiconductor device comprising:

a first semiconductor die disposed over a package substrate, said first semiconductor die coupled to said package substrate;

a plurality of wire bonds coupled to said first semiconductor die and coupled to said package substrate for electrically coupling said first semiconductor die to said package substrate;

a first layer of encapsulant disposed over said first semiconductor die and disposed over said plurality of wire bonds so as to completely cover said plurality of wire bonds; and

a second semiconductor die disposed over said first layer of encapsulant and coupled to said first layer of encapsulant, said second semiconductor die electrically coupled to said package substrate.

2. (original) The packaged semiconductor device of Claim 1 wherein said second semiconductor die is directly coupled to said first layer of encapsulant using adhesive.

3. (original) The packaged semiconductor device of Claim 2 wherein said second semiconductor die at least partially overlies said first semiconductor die.
4. (previously presented) The packaged semiconductor device of Claim 2 wherein only portions of said first layer of encapsulant, portions of said plurality of wire bonds and said adhesive extend between said first semiconductor die and said second semiconductor die.
5. (original) The packaged semiconductor device of Claim 2 wherein no spacer is disposed between said first semiconductor die and said second semiconductor die.
6. (original) The packaged semiconductor device of Claim 2 wherein said package substrate is a ball grid array package substrate.
7. (previously presented) The packaged semiconductor device of Claim 6 further comprising:
  - an additional set of wire bonds, said additional set of wire bonds coupled to said second semiconductor die and coupled to said ball grid array package substrate for electrically coupling said second semiconductor die to said ball grid array package substrate; and
  - a second layer of encapsulant disposed over said second semiconductor die and disposed over said additional set of wire bonds.

Docket No.: IDT-1742.DIV  
Application No.: 10/649123  
Reply to Communication Mailed on August 13, 2004

8. (currently amended) The packaged semiconductor device of Claim 4 2 wherein said adhesive comprises a silver-filled epoxy adhesive.

9. (canceled)

10. (canceled)

11. (canceled)

12. (canceled)

13. (canceled)

14. (canceled)

15. (canceled)

16. (canceled)

17. (canceled)

18. (canceled)

19. (canceled)

20. (canceled)

9 21. (currently amended) A packaged semiconductor device comprising:

a first semiconductor die disposed over a package substrate, said first semiconductor die coupled to said package substrate;

a plurality of wire bonds coupled to said first semiconductor die and coupled to said package substrate for electrically coupling said first semiconductor die to said package substrate;

a first layer of encapsulant disposed over said first semiconductor die and disposed over said plurality of wire bonds so as to completely cover said plurality of wire bonds; and

a second semiconductor die disposed over said first layer of encapsulant, said second semiconductor die attached to said first layer of encapsulant using adhesive, said second semiconductor die electrically coupled to said package substrate.

~~10~~ 22. (currently amended) The packaged semiconductor device of Claim 9 21 wherein said second semiconductor die at least partially overlies said first semiconductor die.

~~44~~ 23. (currently amended) The packaged semiconductor device of Claim ~~9~~ 21 wherein only portions of said first layer of encapsulant, portions of said plurality of wire bonds and said adhesive extend between said first semiconductor die and said second semiconductor die.

~~42~~ 24. (currently amended) The packaged semiconductor device of Claim ~~9~~ 21 wherein no spacer is disposed between said first semiconductor die and said second semiconductor die.

~~43~~ 25. (currently amended) The packaged semiconductor device of Claim ~~42~~ 24 wherein said package substrate is a ball grid array package substrate.

~~44~~ 26. (currently amended) The packaged semiconductor device of Claim ~~9~~ 21 further comprising:

an additional set of wire bonds, said additional set of wire bonds coupled to said second semiconductor die and coupled to said package substrate for electrically coupling said second semiconductor die to said package substrate.

~~45~~ 27. (currently amended) The packaged semiconductor device of Claim ~~44~~ 26 further comprising:

a second layer of encapsulant disposed over said second semiconductor die and disposed over said additional set of wire bonds.

~~16~~ 28. (currently amended) The packaged semiconductor device of Claim ~~9~~ 21 wherein said adhesive comprises a silver-filled epoxy adhesive.

~~17~~ 29. (currently amended) A packaged semiconductor device comprising:

a first semiconductor die disposed over a package substrate, said first semiconductor die coupled to said package substrate;

a first set of wire bonds coupled to said first semiconductor die and coupled to said package substrate for electrically coupling said first semiconductor die to said package substrate;

a first layer of encapsulant disposed over said first semiconductor die and disposed over said first set of wire bonds so as to completely cover said first set of wire bonds;

a second semiconductor die disposed over said first layer of encapsulant, said second semiconductor die attached to said first layer of encapsulant using adhesive; and

a second set of wire bonds, said second set of wire bonds coupled to said second semiconductor die and coupled to said package substrate for electrically coupling said second semiconductor die to said package substrate.

~~18~~ 30. (currently amended) The packaged semiconductor device of Claim ~~17~~ 29

further comprising:

a second layer of encapsulant, said second layer of encapsulant disposed over said second semiconductor die and disposed over said second set of wire bonds.

~~19~~ 31. (currently amended) The packaged semiconductor device of Claim ~~17~~ 29

wherein only portions of said first layer of encapsulant, portions of said first set of wire bonds and said adhesive extend between said first semiconductor die and said second semiconductor die.

~~20~~ 32. (currently amended) The packaged semiconductor device of Claim ~~17~~ 29

wherein no spacer is disposed between said first semiconductor die and said second semiconductor die.

Docket No.: IDT-1742.DIV  
Application No.: 10/649123  
Reply to Communication Mailed on August 13, 2004

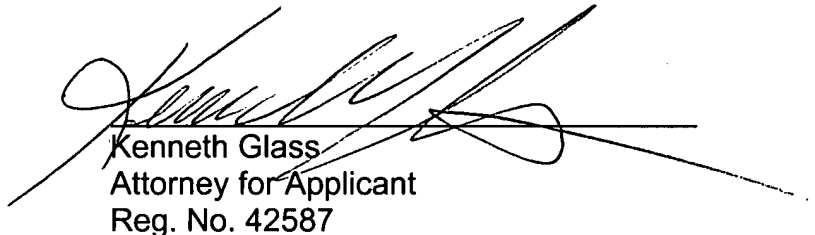
**Conclusion**

Applicant has revised the Amendments to the Claims section to indicate that original claims 9-20 have been canceled.

Claims 1-8 and 21-32 are pending in the present application. Applicant has made a diligent effort to place the claims in condition for allowance. However, should there remain unresolved issues that require adverse action, it is respectfully requested that the Examiner telephone Kenneth Glass, Applicant's Attorney at (408) 354-4448 so that such issues may be resolved as expeditiously as possible.

Respectfully Submitted,

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